SN74LVC821 10-BIT BUS-INTERFACE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS304A - MARCH 1993 - REVISED JULY 1995

 EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process 	DB, DW, OR PW PACKAGE (TOP VIEW)	
 Typical V_{OLP} (Output Ground Bounce) 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	OE (1 24) V _{CC}	
 Typical V_{OHV} (Output V_{OH} Undershoot) 2 V at V_{CC} = 3.3 V, T_A = 25°C 	2D [] 3 22] 2Q 3D [] 4 21] 3Q	
 Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17 	4D	
Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DD)	6D []7 18] 6Q 7D []8 17] 7Q 8D []9 16] 8Q	
(DB), and Thin Shrink Small-Outline (PW) Packages	9D 10 15 9Q	
● Inputs Accept Voltages to 5.5 V	10D []11 14 [] 10Q GND []12 13 [] CLK	

description

This 10-bit bus-interface flip-flop is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVC821 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The ten flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the device provides true data at the Q outputs.

A buffered output-enable (\overline{OE}) input can be used to place the ten outputs in either a normal logic state (high or low level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

The output-enable (\overline{OE}) input does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVC821 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each flip-flop)

	INPUTS			OUTPUT
Ō	Ē	CLK	٥	a
L		1	Н	Н
L		1	L	L
L		H or L	x	Q ₀
H		Х	х	Z

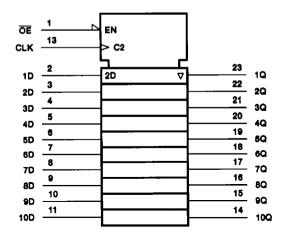
EPIC is a trademark of Texas Instruments Incorporated.



SN74LVC821 10-BIT BUS-INTERFACE FLIP-FLOP WITH 3-STATE OUTPUTS

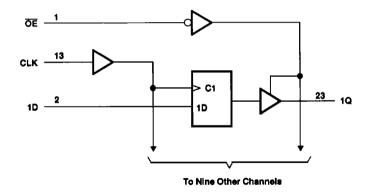
SCASSMA - MARCH 1993 - REVISED JULY 1996

logic symbolt



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SN74LVC821 10-BIT BUS-INTERFACE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS304A - MARCH 1993 - REVISED JULY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} 0.5 V to 6.5 V Input voltage range, V_{I} (see Note 1)0.5 V to 6.5 V Output voltage range, V_{I} (see Notes 1 and 2)0.5 V to V_{CC} + 0.5 V Input clamp current, I_{IK} (V_{I} < 0)50 mA Output clamp current, I_{OK} (V_{O} < 0 or V_{O} > V_{CC}) ±50 mA Continuous output current, I_{O} (V_{O} = 0 to V_{CC}) ±50 mA Continuous current through V_{CC} or GND ±100 mA Maximum power dissipation at T_{A} = 55°C (in still air) (see Note 3): DB package 0.65 W DW package 1.7 W DW package 0.7 W
DW package 1.7 W PW package 0.7 W Storage temperature range, T _{stg} -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BICMOS Technology.
 Data Book. literature number SCBD002B.

recommended operating conditions (see Note 4)

				MAX	UNIT
vcc	Supply voltage	Operating	2	3.6	3.6 V
		Data retention only	1.5		
VIH	High-level input voltage	V _{CC} = 2.7 V to 3.6 V	2		٧
VIL	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	٧
٧١	Input voltage		0	5.5	٧
VO Output voltage	Output veltage	High or low state	0	VCC	v
	Output voitage	3 state	0	5.5	
IOH High-lev	High-level output current VCC = 2.7 V VCC = 3 V	i	-12	A	
		V _{CC} = 3 V		-24	mA
loL	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
∆t/∆v	t/∆v Input transition rise or fall rate		0	10	ns/V
TA	Operating free-air temperature		-40	85	•C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcct	MIN TYP\$	MAX	UNIT
VOH	I _{OH} = -100 μA	MIN to MAX	V _{CC} -0.2		
	I _{OH} = – 12 mA	2.7 V	2.2		v
		3 V	2.4		
	I _{OH} = -24 mA	3 V	2.2		
	IOL = 100 μA	MIN to MAX		0.2	
V _{OL}	I _{OL} = 12 mA	2.7 V		0.4	V
	IOL = 24 mA	3 V		0.55	
l _l	V _I = 5.5 V or GND	3.6 V	-	±5	μА
loz	V _O ≈ 5.5 V or GND	3.6 V		±10	μА
lcc	V _I = V _{CC} or GND, I _O = 0	3.6 V		10	μA
ΔICC	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500	μА
Ci	V _I = V _{CC} or GND	3.3 V			pF
Co	VO = VCC or GND	3.3 V			рF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

[‡] Typical values are measured at V_{CC} = 3.3 V, T_A = 25°C.